

# 4800W Infrared BGA Rework Station WDS 580 SMT Soldering Equipment For Rework Chips

### **Basic Information**

- Place of Origin:
- Brand Name:
- Certification:
- Model Number:
- Minimum Order Quantity: 1 UNIT
- Packaging Details: Wooden case
- Payment Terms: T/T, Western Union, MoneyGram

China WDS

CE

WDS-580

4800W

Max 800W

Max 1200W

Max 2700W

0.3-5mm

Supply Ability: 150 UNITS PER MONTH



## **Product Specification**

- Total Power:
- Upper Hot Air Heater:
- Down Hot Air Heater:
- Bottwm IR Heater:
- PCB Thickness:
- Highlight:
- 4800W Infrared BGA Rework Station, WDS 580 Infrared BGA Rework Station, WDS 580 SMT Soldering Equipment

**Our Product Introduction** 

#### Used for PCB Chip Telephone Mobile WDS-580 Simple Manual BGA Rework Station

#### Feature :

**1.**Adopted with Linear slider, so all the three axles (X, Y, and Z) can do fine tuning and quick orientation with perfect positioning accuracy and speedily maneuverability.

2. Equipped with touch panel interface and PLC controlling to ensure it work stably and reliably. And it can storage multiple temperature profiling data of users. With password protection and modification function while power on. The temperature profiles will be displayed on the touch screen.

3. Three temperature zones to heat up independently, hot air heat up between up and down zones, IR heat in the bottom, temperature precise control is in±3°C. The upper temperature zone can be moved freely according to needs, the second zone can be adjusted up and down. The top and bottom heaters can be set several segments control at the same time. IR heating zone can be adjusted output power in the light of operation requirements.

4. The hot air nozzle can be rotated in 360 degree, the IR heater in the bottom can heat up the PCB board uniformly.

5. High accuracy K-type thermocouple closed-loop controlling. It can test temperature accurately through external temperature measurement interface, PCB board positioned by closed V-shape slot. The flexible and convenient universal jigs can prevent any damage or PCB deformation as well as it is suitable for all size of BGA package.

6.Large power fan to cool down the PCB quickly. The built-in vacuum pump and external vacuum nozzle is able to take BGA chips out easily.

7. Having alarm prompt function after welding is done, specially added early warning function for convenient operation.

8. It has Passed CE certificate. It is equipped with emergency stop switch and protection equipment to power off automatically when abnormal accident happened. Under this situation that temperature is out of control, circuit can automatically cut off the power with double over temperature protection function.

Technology Parameter:	
Total Power	4800W
Upper Heating Power	800W
Lower Heating Power	1200W
Infrared Heating Power	2700W(1200W is controlled)
Power supply	(Single Phase) AC 220V±10 50Hz
Location way	V-shape card slot + Universal jigs
Temperature Controlling	K-type thermocouple closed loop control, independent temperature control, precision up to ±3 degree
Electrical Material	Touch screen + Temperature control module + PLC control
Max PCB size	400×370mm
Min PCB size	10×10mm
Sensor	1 unit
PCB Thickness	0.3-5mm
Suitable Chip Size	1*1mm-60*60mm
Machine Size	650×590×600mm
Weight	Net 40kg

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Shenzhen Wisdomshow Technology Co., Itd

+86 17727914291

Mia@wdsbga.cn 😥 bgaxraymachine.com

No.6, Haosi Western Industry, Shangjing Town, Bao'an District, Shenzhen, China